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## **FDD5N50**

# N-Channel UniFET<sup>TM</sup> MOSFET 500 V, 4 A, 1.4 $\Omega$

#### **Features**

- $R_{DS(on)}$  = 1.15  $\Omega$  (Typ.) @  $V_{GS}$  = 10 V,  $I_D$  = 2 A
- Low Gate Charge (Typ. 11 nC)
- Low C<sub>rss</sub> (Typ. 5 pF)
- · 100% Avalanche Tested
- RoHS Compliant

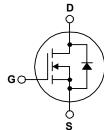
## **Applications**

- LCD/LED/PDP TV
- Lighting
- · Uninterruptible Power Supply

## **Description**

UniFET<sup>TM</sup> MOSFET is ON Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





## **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted.

|   | Parameter   |                                       | Parameter  |   | FDD5N50TM-WS | Unit |
|---|---|---------------------------------------|--|---|--------------|------|
| Drain to Source Voltage                 |   |                                       | 500  | V   |              |      |
| Gate to Source Voltage                  |   |                                       | ±30  | V   |              |      |
| Drain Current                           | - Continuous (T <sub>C</sub> = 25°C)  |                                       | 4  | А   |              |      |
| Diam Current                            | - Continuous (T <sub>C</sub> = 100°C)   | - Continuous (T <sub>C</sub> = 100°C) |  | A   |              |      |
| Drain Current                           | - Pulsed  | (Note 1)                              | 16   | Α   |              |      |
| Single Pulsed Avalanche Energy (Note 2) |   | 256                                   | mJ   |   |              |      |
| Avalanche Current                       |   | (Note 1)                              | 4  | Α   |              |      |
| Repetitive Avalanche Ene                | rgy   | (Note 1)                              | 4  | mJ  |              |      |
| Peak Diode Recovery dv/                 | dt  | (Note 3)                              | 4.5  | V/ns  |              |      |
| Dawer Dissination                       | (T <sub>C</sub> = 25°C)   |                                       | 40   | W   |              |      |
| Power Dissipation                       | - Derate Above 25°C   |                                       | 0.3  | W/°C  |              |      |
| Operating and Storage Temperature Range |   | -55 to +150                           | °C   |   |              |      |
| Maximum Lead Temperat                   | ure for Soldering, 1/8" from Case for 5   | Seconds                               | 300  | °C  |              |      |
|   | Gate to Source Voltage  Drain Current  Drain Current  Single Pulsed Avalanche Avalanche Current  Repetitive Avalanche Ene Peak Diode Recovery dv/d  Power Dissipation  Operating and Storage Te |                                       | $ \begin{array}{c} \text{Drain to Source Voltage} \\ \text{Gate to Source Voltage} \\ \\ \text{Drain Current} \\ \\ \text{Pulsed} \\ \\ \text{Continuous } (T_C = 25^{\circ}C) \\ \\ \text{- Continuous } (T_C = 100^{\circ}C) \\ \\ \text{- Pulsed} \\ \\ \text{(Note 1)} \\ \\ \text{Single Pulsed Avalanche Energy} \\ \text{(Note 2)} \\ \\ \text{Avalanche Current} \\ \text{(Note 1)} \\ \\ \text{Repetitive Avalanche Energy} \\ \text{(Note 1)} \\ \\ \text{Peak Diode Recovery dv/dt} \\ \\ \text{Power Dissipation} \\ \\ \text{($T_C = 25^{\circ}C$)} \\ \\ \text{- Derate Above $25^{\circ}C$} \\ \end{array} $ | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ |              |      |

## **Thermal Characteristics**

| Symbol          | Parameter                                     | FDD5N50TM-WS | Unit  |
|-----------------|---|--------------|-------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case, Max.    | 1.4          | °C/W  |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient, Max. | 110          | 30/00 |

## **Package Marking and Ordering Information**

| Part Number  | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity   |
|--------------|----------|---------|----------------|-----------|------------|------------|
| FDD5N50TM-WS | FDD5N50  | DPAK    | Tape and Reel  | 330 mm    | 16 mm      | 2500 units |

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

| Symbol                                  | Parameter                                    | Test Conditions                                     | Min. | Тур. | Max. | Unit |
|---|--|---|------|------|------|------|
| Off Charac                              | cteristics                                   |   |      |      |      |      |
| BV <sub>DSS</sub>                       | Drain to Source Breakdown Voltage            | $I_D = 250 \mu A, V_{GS} = 0 V, T_J = 25^{\circ} C$ | 500  | -    | -    | V    |
| ΔBV <sub>DSS</sub><br>/ ΔT <sub>J</sub> | Breakdown Voltage Temperature<br>Coefficient | $I_D$ = 250 $\mu$ A, Referenced to 25°C             | -    | 0.6  | -    | V/°C |
| ı                                       | Zero Gate Voltage Drain Current              | V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V      | -    | -    | 1    | ^    |
| IDSS                                    | Zero Gate voltage Drain Current              | $V_{DS} = 400 \text{ V}, T_C = 125^{\circ}\text{C}$ | -    | -    | 10   | μA   |
| I <sub>GSS</sub>                        | Gate to Body Leakage Current                 | V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V      | -    | -    | ±100 | nA   |

#### **On Characteristics**

| V <sub>GS(th)</sub> | Gate Threshold Voltage               | $V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$   | 3.0 | -    | 5.0 | V |
|---------------------|--------------------------------------|--|-----|------|-----|---|
| R <sub>DS(on)</sub> | Static Drain to Source On Resistance | $V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$   | -   | 1.15 | 1.4 | Ω |
| 9 <sub>FS</sub>     | Forward Transconductance             | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 2 A | -   | 4.3  | -   | S |

## **Dynamic Characteristics**

| C <sub>iss</sub>    | Input Capacitance             | V 05 V V 0 V  | -    | 480 | 640 | pF |
|---------------------|-------------------------------|---|------|-----|-----|----|
| C <sub>oss</sub>    | Output Capacitance            | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,<br>f = 1 MHz | -    | 66  | 88  | pF |
| C <sub>rss</sub>    | Reverse Transfer Capacitance  | 1 - 1 101112  | -    | 5   | 8   | pF |
| Q <sub>g(tot)</sub> | Total Gate Charge at 10V      | V <sub>DS</sub> = 400 V, I <sub>D</sub> = 5 A,              | -    | 11  | 15  | nC |
| $Q_{gs}$            | Gate to Source Gate Charge    | V <sub>GS</sub> = 10 V                                      | -    | 3   | -   | nC |
| $Q_{gd}$            | Gate to Drain "Miller" Charge | (Note   | 4) _ | 5   | -   | nC |

## **Switching Characteristics**

| t <sub>d(on)</sub>  | Turn-On Delay Time  |  | - | 13 | 36 | ns |
|---------------------|---------------------|--|---|----|----|----|
| t <sub>r</sub>      | Turn-On Rise Time   | $V_{DD} = 250 \text{ V}, I_D = 5 \text{ A},$ | - | 22 | 54 | ns |
| t <sub>d(off)</sub> | Turn-Off Delay Time | $V_{GS}$ = 10 V, $R_G$ = 25 $\Omega$         | - | 28 | 66 | ns |
| t <sub>f</sub>      | Turn-Off Fall Time  | (Note 4)                                     | - | 20 | 50 | ns |

## **Drain-Source Diode Characteristics**

| I <sub>S</sub>  | Maximum Continuous Drain to Source Diode Forward Current                           |   | - | -   | 4   | Α  |
|-----------------|--|---|---|-----|-----|----|
| I <sub>SM</sub> | Maximum Pulsed Drain to Source Diode Forward Current                               |   |   | -   | 16  | Α  |
| $V_{SD}$        | Drain to Source Diode Forward Voltage V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 4 A |   | - | -   | 1.4 | V  |
| t <sub>rr</sub> | Reverse Recovery Time  | V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 5 A, | - | 300 | -   | ns |
| Q <sub>rr</sub> | Reverse Recovery Charge  | dI <sub>F</sub> /dt = 100 A/μs                |   | 1.8 | -   | μС |

#### Notes:

- ${\it 1:} \ \ {\it Repetitive\ rating: pulse-width\ limited\ by\ maximum\ junction\ temperature.}$
- 2: L = 32 mH,  $I_{AS}$  = 4 A,  $V_{DD}$  = 50 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C.
- 3:  $I_{SD} \le 4$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , starting  $T_J = 25^{\circ}C$ .
- ${\bf 4:} \ \ {\bf Essentially\ independent\ of\ operating\ temperature\ typical\ characteristics.}$

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

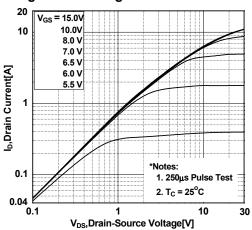
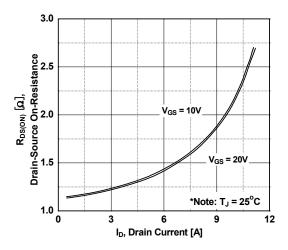


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage



**Figure 5. Capacitance Characteristics** 

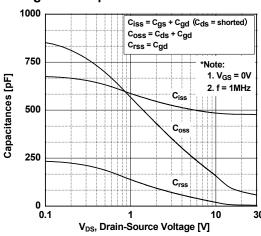


Figure 2. Transfer Characteristics

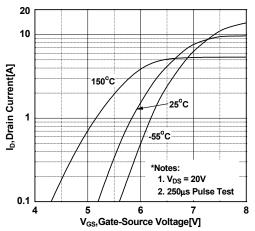


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

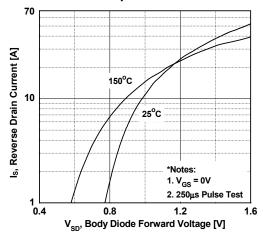
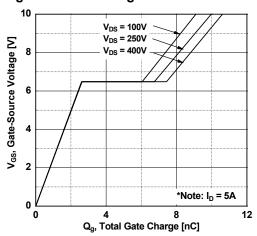


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

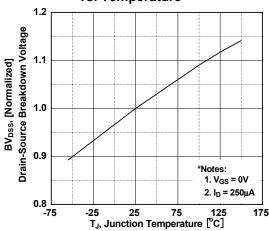


Figure 8. On-Resistance Variation vs. Temperature

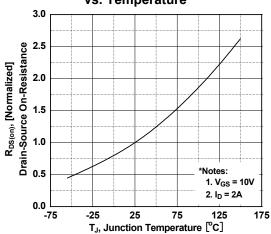


Figure 9. Maximum Safe Operating Area

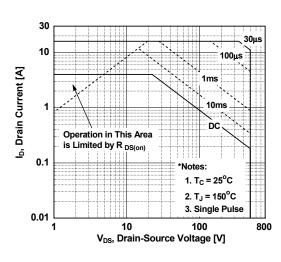


Figure 10. Maximum Drain Current vs. Case Temperature

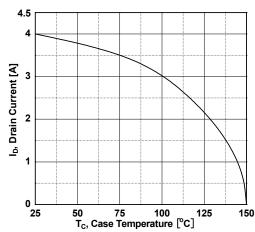
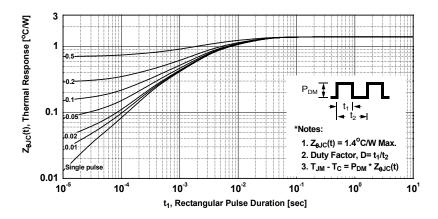


Figure 11. Transient Thermal Response Curve



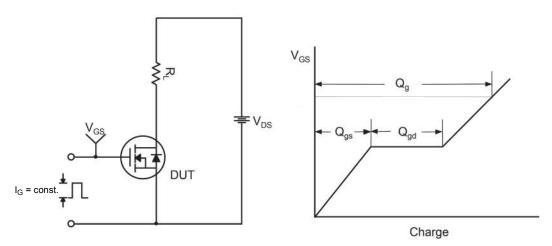


Figure 12. Gate Charge Test Circuit & Waveform

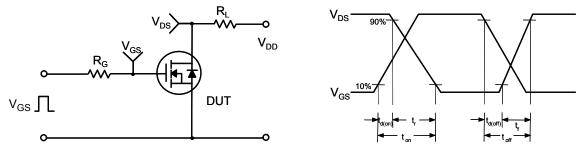


Figure 13. Resistive Switching Test Circuit & Waveforms

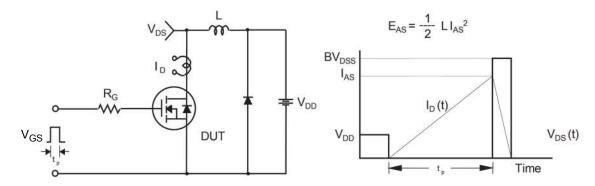
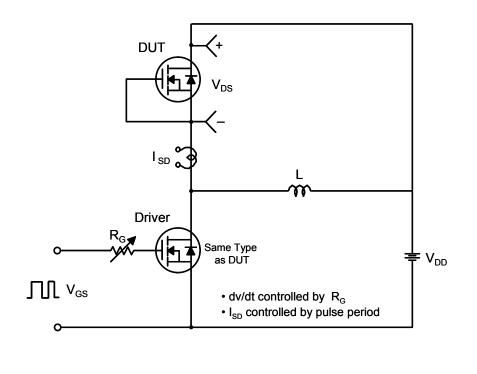


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



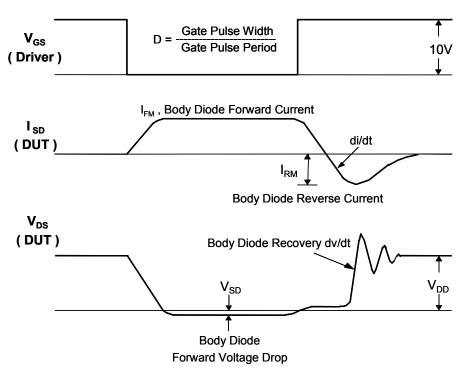


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

## **Mechanical Dimensions**

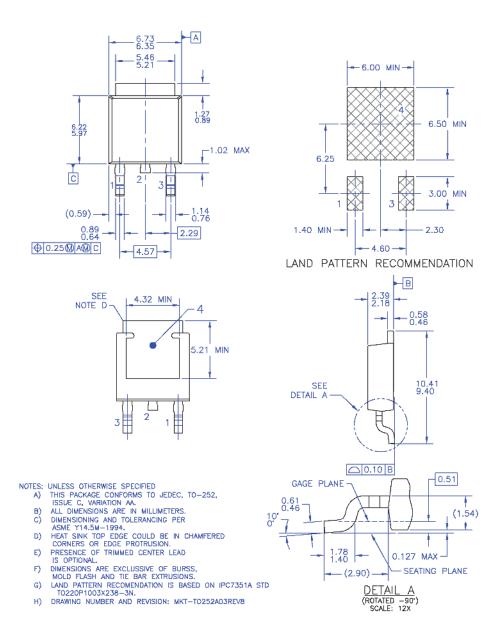


Figure 16. TO252 (D-PAK), Molded, 3-Lead, Option AA&AB

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